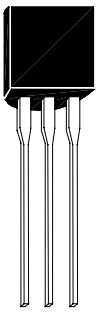
HA8050S

NPN EPITAXIAL PLANAR TRANSISTOR



TO-92

Description

The HA8550S is designed for general purpose amplifier applications.

Features

- High DC Current Gain (hFE=100~500 at IC=150mA)
- Complementary to HA8550S

Absolute Maximum Ratings

- Maximum Temperatures
  Storage Temperature ..... -55 ~ +150 °C
  Junction Temperature ..... +150 °C Maximum
- Maximum Power Dissipation
  Total Power Dissipation (Ta=25°C) ..... 625 mW
- Maximum Voltages and Currents (Ta=25°C)
  VCBO Collector to Base Voltage ..... 25 V
  VCEO Collector to Emitter Voltage ..... 20 V
  VEBO Emitter to Base Voltage ..... 5 V
  IC Collector Current ..... 700 mA

Characteristics (Ta=25°C)

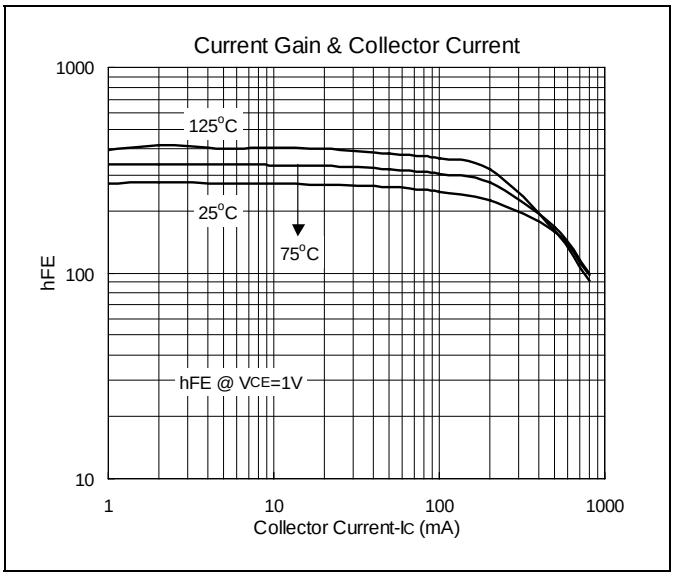
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	25	-	-	V	IC=10uA
BVCEO	20	-	-	V	IC=1mA
BVEBO	5	-	-	V	IE=10uA
ICBO	-	-	1	uA	VCB=20V
IEBO	-	-	100	nA	VEB=6V
*VCE(sat)	-	-	0.5	V	IC=0.5A, IB=50mA
VBE(on)	-	-	1	V	VCE=1V, IC=150mA
*hFE1	100	-	500		VCE=1V, IC=150mA
*hFE2	-	170	-		VCE=1V, IC=500mA
fT	150	-	-	MHz	VCE=10V, IC=20mA, f=100MHz
Cob	-	-	10	pF	VCB=10V, f=1MHz

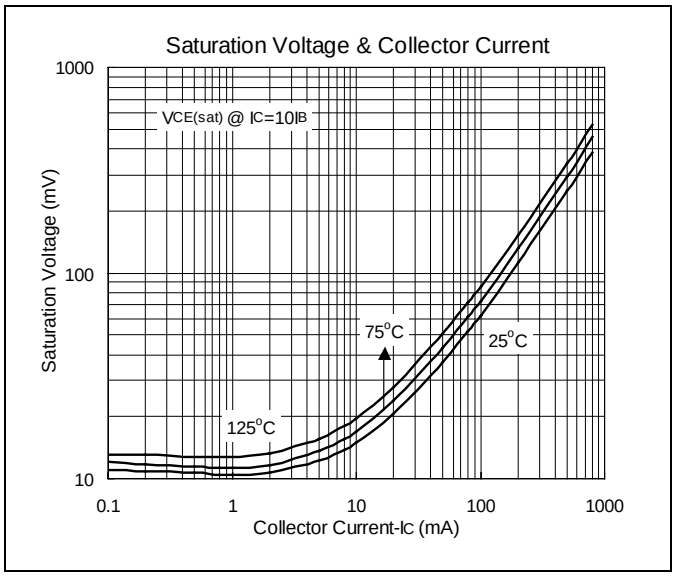
*Pulse Test: Pulse Width ≤380us, Duty Cycle≤2%

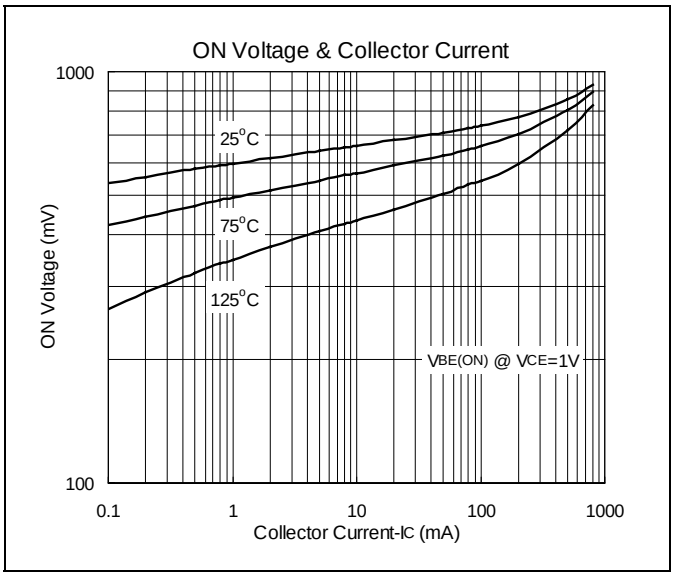
Classification on hFE

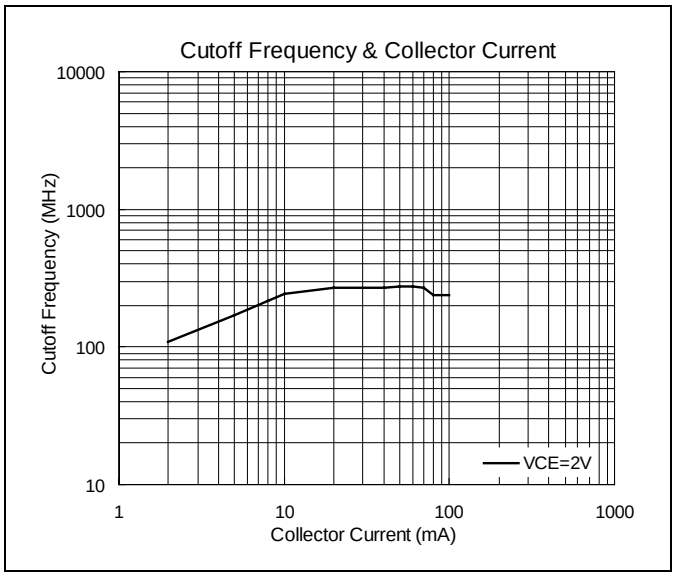
Rank	C	D	E
hFE1	100~200	150~300	250-500

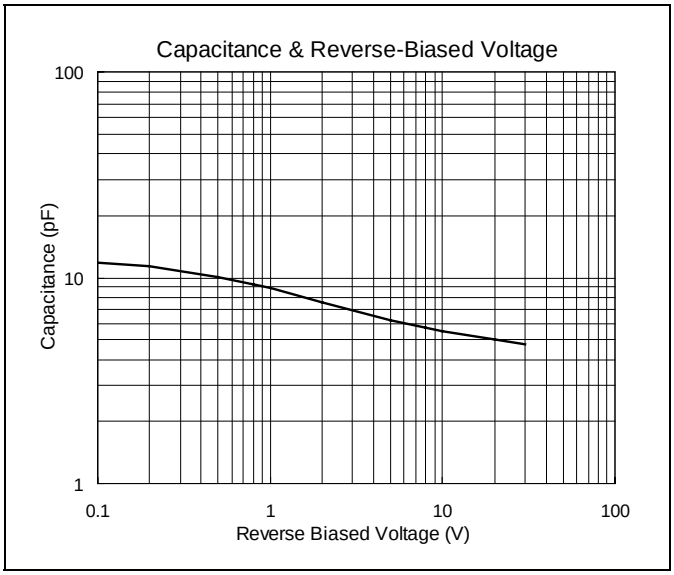
Characteristics Curve

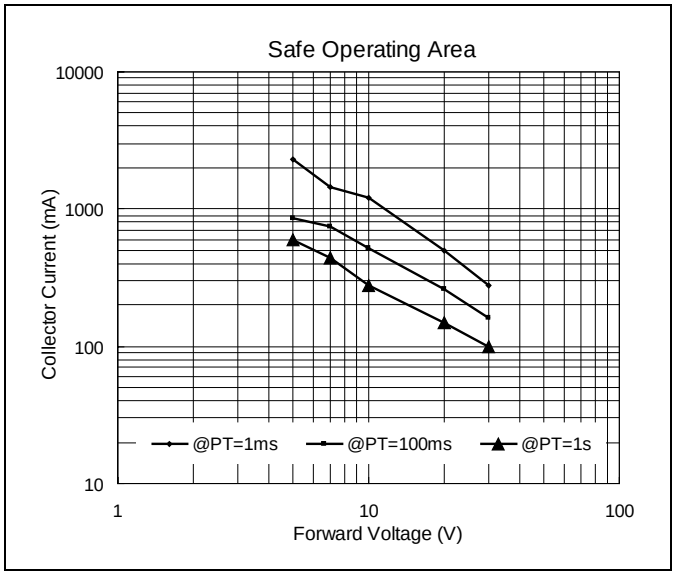


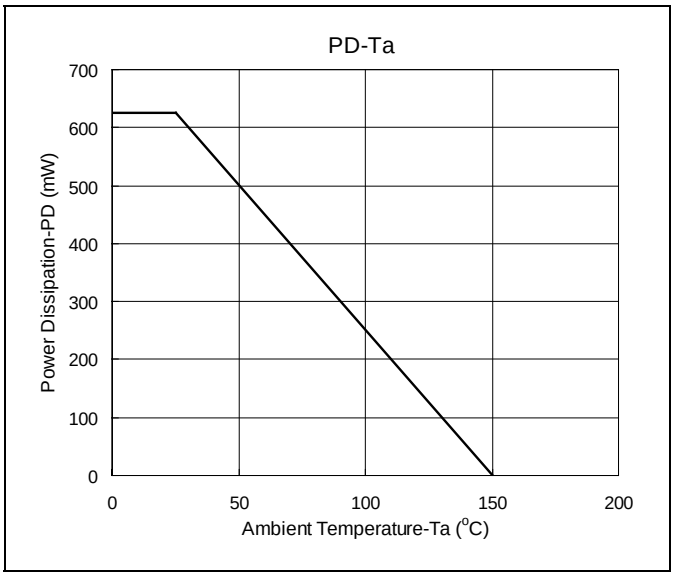




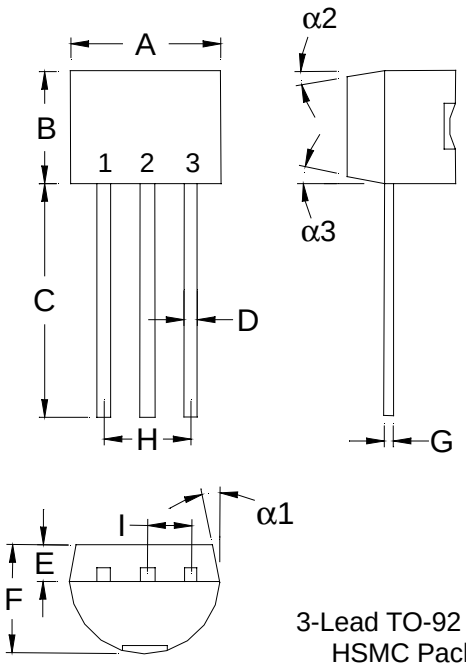




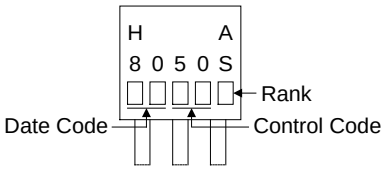



PD-Ta
Power Dissipation-PD (mW)
700
600
500
400
300
200
100
0
0
50
100
150
200
Ambient Temperature-Ta (°C)

TO-92 Dimension



Marking:



Style: Pin 1.Emitter 2.Base 3.Collector

3-Lead TO-92 Plastic Package
HSMC Package Code: A

*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1704	0.1902	4.33	4.83	G	0.0142	0.0220	0.36	0.56
B	0.1704	0.1902	4.33	4.83	H	-	*0.1000	-	*2.54
C	0.5000	-	12.70	-	I	-	*0.0500	-	*1.27
D	0.0142	0.0220	0.36	0.56	α1	-	*5°	-	*5°
E	-	*0.0500	-	*1.27	α2	-	*2°	-	*2°
F	0.1323	0.1480	3.36	3.76	α3	-	*2°	-	*2°

Notes: 1.Dimension and tolerance based on our Spec. dated Apr. 25,1996.
2.Controlling dimension: millimeters.
3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material:

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class : UL94V-0

Important Notice:

- All rights are reserved. Reproduction in whole or in part is prohibited without the prior written approval of HSMC.
- HSMC reserves the right to make changes to its products without notice.
- ***HSMC semiconductor products are not warranted to be suitable for use in Life-Support Applications, or systems.***
- HSMC assumes no liability for any consequence of customer product design, infringement of patents, or application assistance.

Head Office And Factory:

- **Head Office** (Hi-Sincerity Microelectronics Corp.): 10F.,No. 61, Sec. 2, Chung-Shan N. Rd. Taipei Taiwan R.O.C.
  Tel: 886-2-25212056 Fax: 886-2-25632712, 25368454
- **Factory 1:** No. 38, Kuang Fu S. Rd., Fu-Kou Hsin-Chu Industrial Park Hsin-Chu Taiwan. R.O.C
  Tel: 886-3-5983621~5 Fax: 886-3-5982931